

<b>PAB Materials Test System</b>	
<b>Date of Receipt</b>	8/24/2009
<b>Sample Name/Description</b>	Master Bond glue EP29LPSP
<b>Sample</b>	
<b>Composition:</b>	Two component, heat cured epoxy
<b>Picture Location:</b>	
<b>Density:</b>	x
<b>Weight:</b>	10.5g sample
<b>Dimensions/Area:</b>	app. 70mm dia. 2mm thick glue disc
<b>Source:</b>	Cary Kendziora
<b>Preparation:</b>	
<b>Submerging in LAr or LN2</b>	x
<b>Zero Test</b>	x
<b>Time in the airlock(hrs)</b>	
<b>Purge:</b>	7/16/09 overnight and 3h with Luke vapor
<b>Vacuum:</b>	x
<b>Vapor Test 1</b>	
<b>Start Time/Date, End Time/Date :</b>	7/20/2009 10:30am, 7/22/2009 9:00am
<b>PrM run # :</b>	5534
<b>Condenser state:</b>	On
<b>Filter state:</b>	On
<b>O2 reading:</b>	0.00ppm
<b>H2O reading:</b>	1.63ppb
<b>Temperature:</b>	163K
<b>Lifetime:</b>	2.2ms 2mins after, 1.3ms 7hrs after
<b>Vapor Test 2</b>	x
<b>Start Time/Date, End Time/Date :</b>	
<b>PrM run # :</b>	
<b>Condenser state:</b>	
<b>Filter state:</b>	
<b>O2 reading:</b>	
<b>H2O reading:</b>	
<b>Temperature:</b>	
<b>Lifetime:</b>	
<b>Liquid Test</b>	
<b>Start Time/Date, End Time/Date :</b>	7/17/09 8:00am, 7/20/09 10:30am
<b>PrM run # :</b>	5503
<b>Condenser state:</b>	On
<b>Filter state/settings:</b>	On
<b>O2 reading:</b>	0.00ppm
<b>H2O reading:</b>	1.4ppb
<b>Temperature:</b>	95K
<b>Lifetime:</b>	2.2ms before test, 2.9ms 8mins after
<b>Liquid level :</b>	27.9 inches
<b>Results &amp; Comments</b>	Master Bond glue can be used at low temperatures. Historical Data plot in elog 7/20/2009 and 7/22/2009